

Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application.

Please amend claims 1, 3, 5-8, and add new dependent claims 9-14 as follows:

1. (Currently Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming a raised and recessed region in an upper portion of a base substrate;

a second step of growing a semiconductor layer of nitride on said raised and recessed region in said upper portion of said base substrate so that a recessed portion in said raised and recessed region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said third step, the laser beam is irradiated upon said semiconductor layer from the surface opposite to the upper portion of said base substrate, ~~while stress is being generated~~ so as to generate cracks at the interface between the top of the raised portion of the base substrate and the semiconductor layer.

2. (Original) The method of manufacturing a nitride semiconductor substrate according to claim 1, wherein in said third step, the laser beam is irradiated upon at least a raised portion in said raised and recessed region.

3. (Currently Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, ~~while stress is being generated~~ so as to generate cracks at the interface between the top of the raised portion of the base substrate and the semiconductor layer, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said first step, a plurality of grooves extending parallel to each other are formed on said main surface of said base substrate, and

wherein in said third step, the laser beam is irradiated upon at least a raised portion in said irregular region while scanning along raised portions surrounded by said plurality of grooves in said base substrate.

4. (Original) The method of manufacturing a nitride semiconductor substrate according to claim 3, wherein said base substrate comprises sapphire whose main surface is in the {0001} plane orientation, and the direction of the zone axis of each said groove is in the <1-100> direction in said base substrate.

5. (Currently Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, ~~while stress is being generated~~ so as to generate cracks at interface between the top of the raised portion of the base substrate and the semiconductor layer, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said first step, a plurality of island shaped raised portions are formed on the main surface of said base substrate, and

wherein in said third step, a pulsed laser beam is irradiated upon at least a raised portion in said irregular region while scanning in synchronization with said plurality of raised portions in said base substrate.

6. (Currently Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, ~~while stress is being generated~~ so as to generate cracks at the interface between the top of the raised portion of the base substrate and the semiconductor layer, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said third step, the laser beam is irradiated simultaneously upon the plurality of raised portions in said irregular region.

7. (Currently Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, ~~while stress is being generated~~ so as to generate cracks at the interface between the top of the raised portion of the base substrate and the semiconductor layer, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said first step, the area occupied by the recessed portions is about in the range from about 1/5 to about 100 times the area occupied by the raised portions.

8. (Currently Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, ~~while stress is being generated~~ so as to generate cracks at the interface between the top of the raised portion of the base substrate and the semiconductor layer, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said third step, the laser beam is irradiated from the surface opposite to the main surface of said base substrate.

9. (New) The method of manufacturing a nitride semiconductor substrate according to claim 1, wherein said cracks extend in parallel to the main surface of the base substrate.

10. (New) The method of manufacturing a nitride semiconductor substrate according to claim 3, wherein said cracks extend in parallel to the main surface of the base substrate,

11. (New) The method of manufacturing a nitride semiconductor substrate according to claim 5, wherein said cracks extend in parallel to the main surface of the base substrate.

12. (New) The method of manufacturing a nitride semiconductor substrate

accoordng to claim 6, wherein said cracks extend in parallel to the main surface of the base substrate.

13. (New) The method of manufacturing a nitride semiconductor substrate according to claim 7, wherein said cracks extend in parallel to the main surface of the base substrate.

14. (New) The method of manufacturing a nitride semiconductor substrate according to claim 8, wherein said cracks extend in parallel to the main surface of the base substrate.